High-Speed AOI module for MatriX Inspection Systems



MV-200C

High-Speed AOI Module for MatriX AXI Inspection Systems

MatriX offers the **MV-200C** high-speed AOI system as an enhancement to its X2/X2.5 platform of x-ray inspection systems. The AOI module features CyberOptics award-winning strobe inspection module (SIM) technology. SIM uses the strobe technology for on-the-fly area scanning inspection resulting in production speed rates of up to 200cm2/s. At the same time the quality of the captured image is excellent with high resolution. Main applications in combination with the MatriX high-speed AXI systems are component presence and polarity tests.

The **MV-200C** system can be linked with the MatriX proprietary **MIPS\_Process** software environment for closedloop verification and repair.

MIPS\_Process also features statistic process tools for yield control, process analysis and report generation as well as tools for online statistics and process monitoring.



## **Features and Benefits**

- In-line high-speed AOI module based on SIM technology
- Dual fixed angle lighting
- Multicolor CMOS Camera System
- Multiple 5 Megapixel Color CMOS Cameras
- Image Transfer Protocol PCIE
- Resolution: 17µm pixel size (High-resolution setup: 12 µm pixel size)
- Image Processing: Al<sup>2</sup> Technology
- Simple on-line or off-line programming
- CAD Import: Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.)
- Compact, modular design for easy and spacesaving integration into production line

## **Inspection & Process Software**

- MIPS\_Verify link with closed-loop repair
- MIPS\_SPC Real Time with real-time SPC



# **Applications**

- Components Types Inspected
- Component Defect Categories
- Solder Joint Defects Categories
- Other Items Detected
- Component Measurement Categories

Standard SMT (chips, J-lead, gull-wing, etc.), throughhole, odd-form, clips, connectors, header pins, and others

Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and others

Solder bridge, opens, lifted leads, wettability, excess and insufficient solder, debris, and others

Gold-finger contamination, pin-in-hole, bent pins, debris and many others

Component X, Y position and rotation



## **Specifications**

## Facilities

**Dimensions:** 860 mm x 750 mm x 620 mm **Weight:** 65 kg (143.300 lbs.)

#### **Power Requirements:**

100 - 120V 60Hz/ 220 -240V 50Hz/2 amp max.

## Hardware

Processor: Quad-core, dual processor computer
Application Software: Windows-based custom application
Monitor: 19" LCD display
Keyboard: Standard Keyboard
Mouse: Standard Optical Mouse
Communications: RS232 & Ethernet

## X-ray Imaging

Detector type: 3" / 2" image intensifer Camera: 1028 x 1028 pixel, 10 bit Video output: Camera link interface Video display: High resolution 19" TFT

## Inspection features

Inspection Area: 320 mm x 320 mm Optional: 510 mm Component Size (min): 0402 (01005) Lead Pitch: 0.3 mm Component Height Clearance (max): 30 mm

Board Edge Clearance (min): 3.0 mm (0.125 in.) – bottom side only Resolution: 17 micron Lighting: Strobe White Light Scanning speed: up to 200 cm<sup>2</sup>/s

#### For more information, speak with your MatriX representative.

Germany Feldkirchen (Munich) +49.(0)89.189.4140.0 Phone

+49.(0)89.189.4140.98 **Fax** info@m-xt.com **Mail** 

Hildesheim +49.(0)5121.875.8428 **Phone** info@m-xt.com **Mail** 

Hungary Budapest +36.(0)30.876.5038 Phone hungary@m-xt.com Mail

USA San Diego +1.858.536.5050 Phone +1.858.536.50.50 Fax sales@focalspot.com Mail

Singapore +65.6513.5766 Phone +65.6425.5231 Fax singapore@m-xt.com Mail

China Suzhou +86.136.5620.3952 Phone china@m-xt.com Mail

Japan Kagoshima +81.9954.38876 Phone japan@m-xt.com Mail

Brazil Vinhedo-SP +55.1938.7605.35 Phone info@m-xt.com Mail

MatriX Technologies GmbH Dornacher Str. 5 85622 Feldkirchen (Munich) Germany +49.(0)89.189.4140.0 Phone +49.(0)89.189.4140.99 Fax info@m-xt.com m-xt.com

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